

VIA

## Mobile360 M810

Fanless ultra-compact in-vehicle solution for flexible 360° SVS, ADAS and DMS configurations



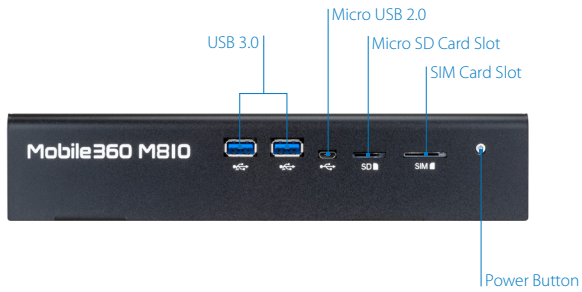
### Features

- Six FAKRA connectors
- Two CAN bus ports
- AWS IoT Greengrass qualified
- VIA ADAS technology including FCW, BSD, LDW, SLD, and DMOD
- VIA SVS technology enabling real-time 360° panoramic display

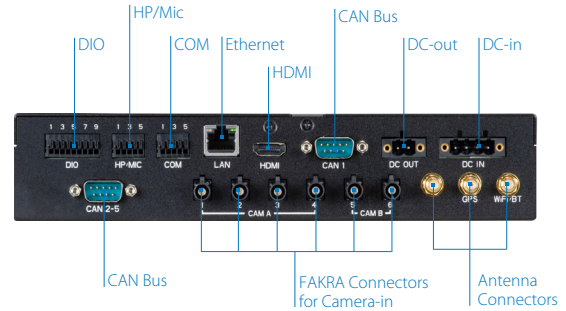
### Specifications

Model Name	Mobile360 M810
<b>Processor</b>	Qualcomm® APQ8096A Embedded Processor - Two high-performance Kryo cores up to 2.054GHz - Two low power Kryo cores up to 1.593GHz
<b>System Memory</b>	4GB LPDDR4 SDRAM
<b>Storage</b>	16GB eMMC flash memory 2 M.2 SATA slots
<b>Graphics</b>	Qualcomm® Adreno™ 530 GPU 3D graphics accelerator with 64-bit addressing 624MHz Graphics engine supporting OpenGL ES 3.1/GEP, GL4.4, DX11.3/4, OpenCL 2.0, Renderscript-Next Supports H.264, VP8, HEVC 8/10-bit, VP9 video decoding up to: 4K@60fps, 1080p@240fps, 8 x 1080p@30fps
<b>Camera-in Interface</b>	2 DS90UB964-Q1 Quad FPD-Link III deserializer Hub
<b>LAN</b>	RTL8111G Ethernet Controller
<b>Wireless Connectivity</b>	AMPAK AP12356_I MiniPCIe Wi-Fi/BT 4.1 module MAX-M8Q-0-10 u-blox 8 GNSS module
<b>Audio</b>	TI 6PAIC3104IRHBRQ1 Audio Codec
<b>HDMI</b>	Integrated HDMI 2.0 transmitter
<b>Expansion I/O</b>	1 MiniPCIe slot (USB only) for 4G module 1 MiniPCIe slot (PCIe/USB) for Wi-Fi/BT module
<b>Front Panel I/O</b>	2 USB 3.0 ports 1 Micro USB 2.0 port (for debugging) 1 Micro SD card slot 1 SIM card slot (optional) 1 Power button
<b>Back Panel I/O</b>	1 HDMI port 1 DIO port 1 COM port 2 CAN bus ports (supports up to five CAN bus) 1 Gigabit Ethernet port 6 FAKRA connectors for camera-in 1 Headphone/Mic-in connector 3 Antenna connectors for Wi-Fi/BT, GPS, and 4G (factory option) 1 4-pole Phoenix 9~36V DC-in 1 2-pole Phoenix 12V DC-out
<b>Power Supply</b>	9~36V DC-in with IGN
<b>Operating System</b>	Yocto 2.3
<b>Operating Temperature</b>	-20°C ~ 70°C
<b>Storage Temperature</b>	-20°C ~ 70°C
<b>Operating Humidity</b>	0~95% (non-condensing)
<b>Vibration Loading During Operation</b>	ISO-16750-3 compliance
<b>Shock During Operation</b>	ISO-16750-3 compliance

## Front Panel External I/O



## Back Panel External I/O



## Specifications

<b>Model Name</b>	<b>Mobile360 M810</b>
<b>Mechanical Construction</b>	Metal chassis housing
<b>Dimensions</b>	236.7mm(W) x 46mm(H) x 180mm(D) (9.32" x 1.81" x 7.09")
<b>Weight</b>	2.2kg (4.85lbs)
<b>Compliance</b>	CE, FCC

## Ordering Information

Part Number	SoC Frequency	Description
M360-810-1Q20A1	Qualcomm® APQ8096A Embedded Processor @ 2.054GHz/1.593GHz	Fanless mobile system with 2.054GHz Qualcomm® APQ8096A Embedded Processor, 4GB LPDDR4 SDRAM, HDMI, 2 USB 3.0, Micro USB 2.0 (debugging), DIO, COM, 2 CAN bus, Gigabit Ethernet, 6 FAKRA connectors for camera-in, Wi-Fi, Bluetooth 4.1, GPS, Micro SD card slot, 2 M.2 slots, 12V DC-out, 9~36V DC-in with IGN

## Optional Accessories

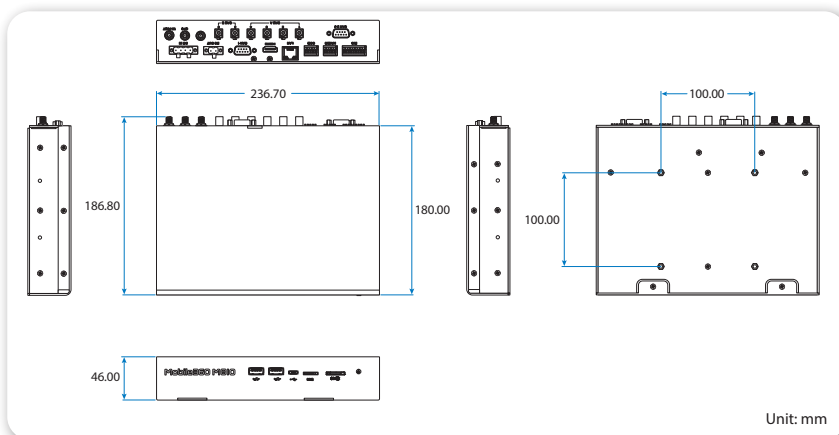
### Camera & Accessories

Part Number	Description
99G40-08075Z	1.0MP FOV-40 720p CMOS automotive-grade camera
99G40-08074Z	1.0MP FOV-190 720p CMOS automotive-grade camera
99G33-230396	10M FAKRA cable
99G33-230406	15M FAKRA cable

### Display Accessories

Part Number	Description
99G73-01034C	10" Resistive touch monitor (1280x800)
99G73-01030C	7" Resistive touch monitor (1280x800)

## Dimensions



## Packing List

Items
Mobile360 M810 system
2 Phoenix plug to DC jacks (DC-in & DC-out)
COM cable (for debugging)
GPS antenna
2 Wi-Fi/BT antennas

